

CLAIMS:

1. A polyimide metal laminate comprising a copper foil and a stainless steel foil or stainless steel foils formed on both sides of a polyimide resin, wherein the polyimide resin which comes in contact with the stainless steel foil or the copper foil has a heat resistance temperature being not less than 350°C, the coefficient of humidity expansion at 32°C being from 1 to 20 ppm/%RH, an average value of the etching rate by a 50 wt % aqueous solution of potassium hydroxide at 80°C being not less than 1.0 $\mu\text{m}/\text{min}$, and the peel strength after heating at 350°C for 60 minutes being not less than 1.0 kN/m.

2. The polyimide metal laminate according to claim 1, wherein the polyimide resin which comes in contact with the stainless steel foil or the copper foil is a thermoplastic polyimide obtained by reacting a diamine with a tetracarboxylic acid dianhydride, the tetracarboxylic acid dianhydride in use is obtained by combining at least one kind of tetracarboxylic acid dianhydride selected from pyromellitic acid dianhydride, p-phenylene bis(trimellitic acid monoester anhydride), 3,3',4,4'-ethylene glycol dibenzoate tetracarboxylic acid dianhydride and 2,2-bis(4-hydroxyphenyl)propane-3,3',4,4'-benzophenone tetracarboxylic acid dianhydride with 3,3',4,4'-benzophenone tetracarboxylic acid dianhydride, and 3,3',4,4'-benzophenone tetracarboxylic acid dianhydride is not less than 5 mole % and not more than 50 mole % of the total tetracarboxylic acid dianhydride in use.

3. The polyimide metal laminate according to claim 1, wherein the polyimide resin which comes in contact with the stainless steel foil or the copper foil is a thermoplastic polyimide obtained by reacting a diamine with a tetracarboxylic acid dianhydride and pyromellitic acid dianhydride is not less than 50 mole % of the total tetracarboxylic acid dianhydride in use.

4. The polyimide metal laminate according to claim 1, wherein the polyimide resin which comes in contact with the stainless steel foil or the copper foil is a thermoplastic polyimide obtained by reacting a diamine with a tetracarboxylic acid dianhydride, and comprises at least one kind of diamine selected from 1,3-bis(3-aminophenoxy)benzene, 4,4'-bis(3-aminophenoxy)biphenyl, 3,3'-diaminobenzophenone and 1,3-bis(3-(3-aminophenoxy)phenoxy)benzene as a diamine in use.

5. A suspension for a hard disk drive prepared from the polyimide metal laminate as described in any one of claims 1 to 4.